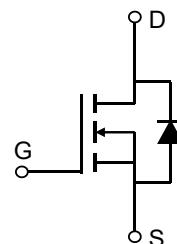


Description

Features

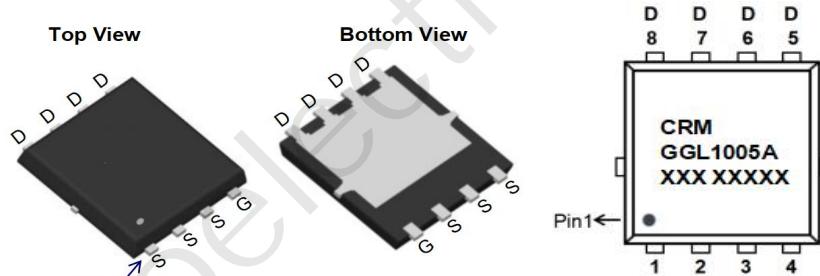
- 100V, 120A
- $R_{DS(ON)}$ Typ = 4mΩ @ V_{GS} = 10V
- $R_{DS(ON)}$ Typ = 5.3mΩ @ V_{GS} = 4.5V
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGGL1005A	CRMGGGL1005A	PDFN5x6-8L	TAPING	13"	5000	50000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	100	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current $T_C = 25^\circ\text{C}$	120	A
	$T_C = 100^\circ\text{C}$	72	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	480	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	248	mJ
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	125	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.4	2	2.6	V
$R_{\text{DS(ON)}}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}, I_D = 30\text{A}$	-	4	5.2	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 20\text{A}$	-	5.3	6.9	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance		-	3655	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$	-	2061	-	pF
C_{rss}	Reverse Transfer Capacitance		-	57	-	pF
Q_g	Total Gate Charge		-	55	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10\text{V}$	-	20	-	nC
Q_{gd}	Gate Drain("Miller") Charge	$V_{DS} = 50\text{V}, I_D = 20\text{A}$	-	12	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime		-	16	-	ns
t_r	Turn-On Rise Time	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$	-	20	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 20\text{A}, R_{\text{GEN}} = 3\Omega$	-	30	-	ns
t_f	Turn-Off Fall Time		-	17	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	120	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	480	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	60	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 20\text{A}, di/dt = 100\text{A/us}$	-	120	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $V_G=10\text{V}$, $R_G=25\text{ohm}$, $L=0.5\text{mH}$, $I_{AS}=31.5\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

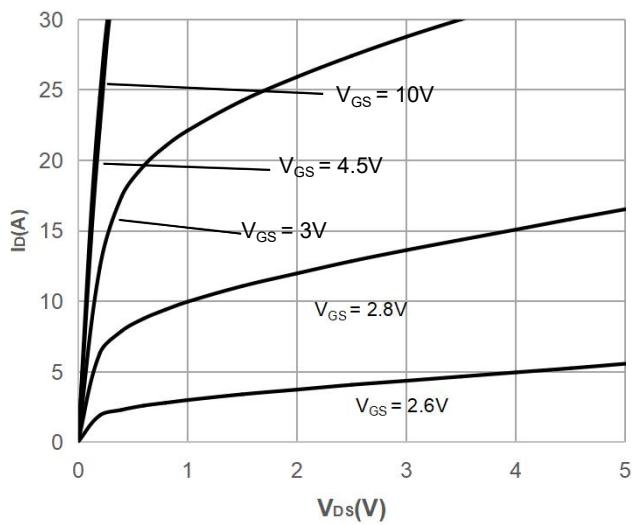


Figure 2: Typical Transfer Characteristics

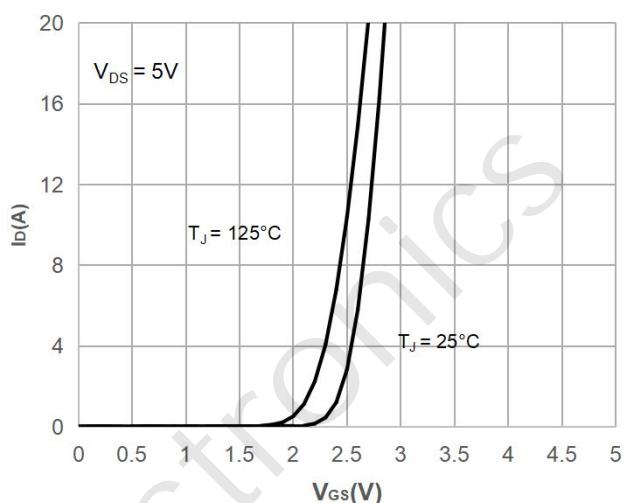


Figure 3: On-resistance vs. Drain Current

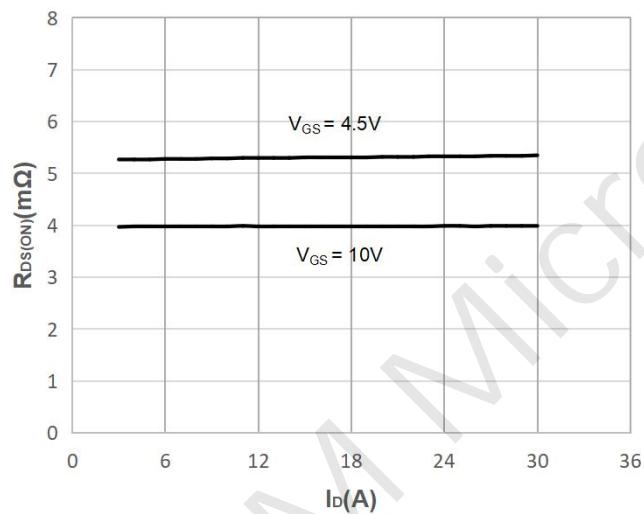


Figure 4: Body Diode Characteristics

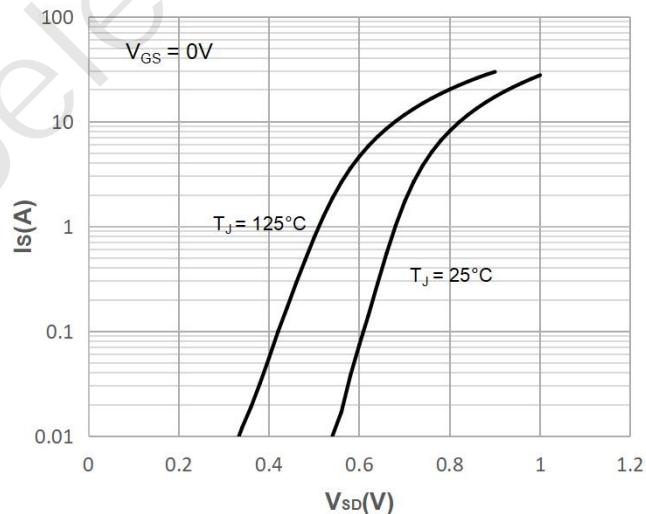


Figure 5: Gate Charge Characteristics

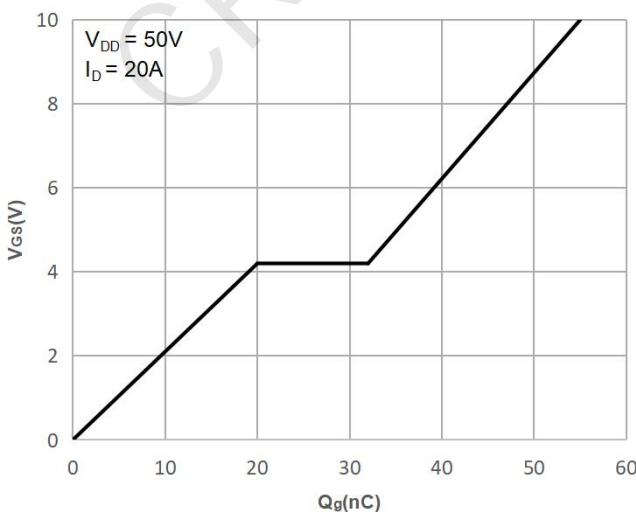
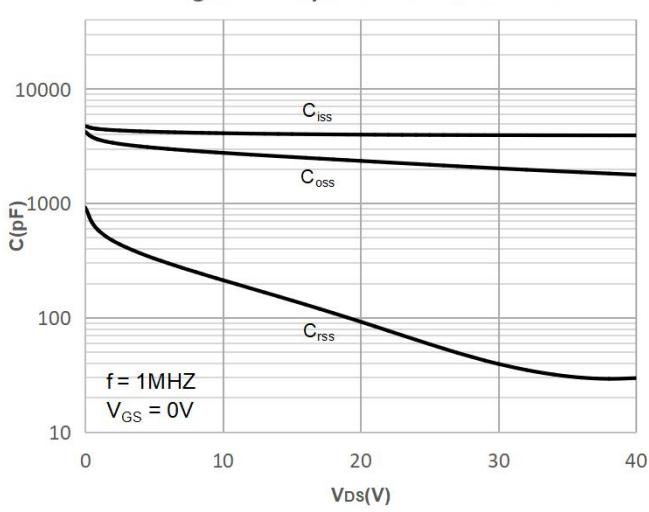


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

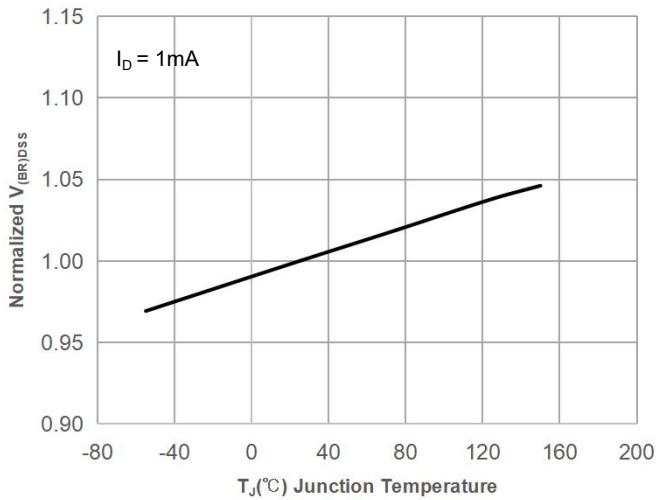


Figure 8: Normalized on Resistance vs. Junction Temperature

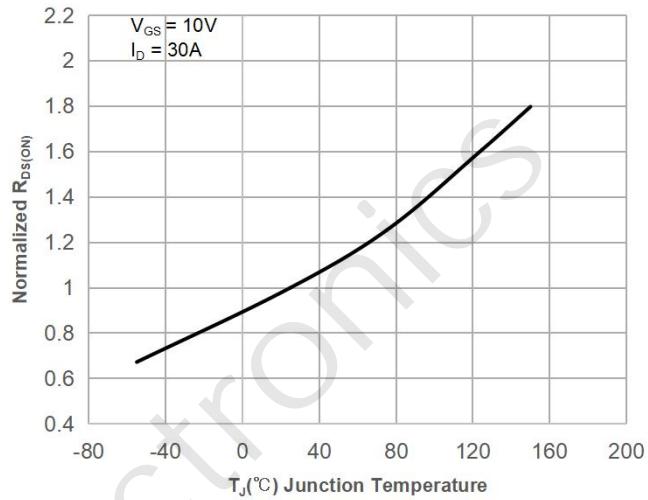


Figure 9: Maximum Safe Operating Area

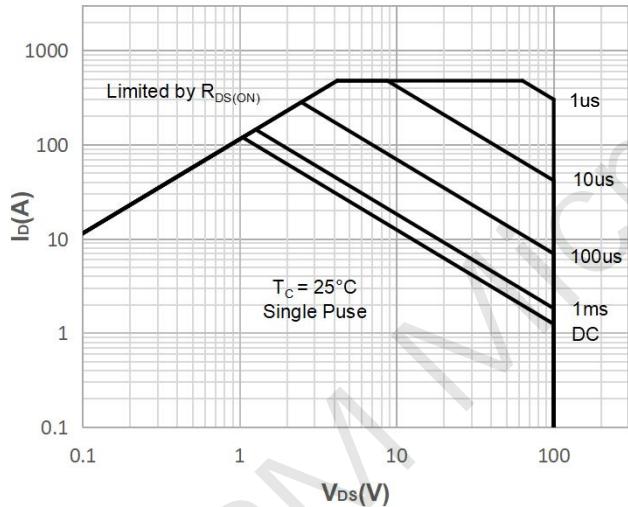


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

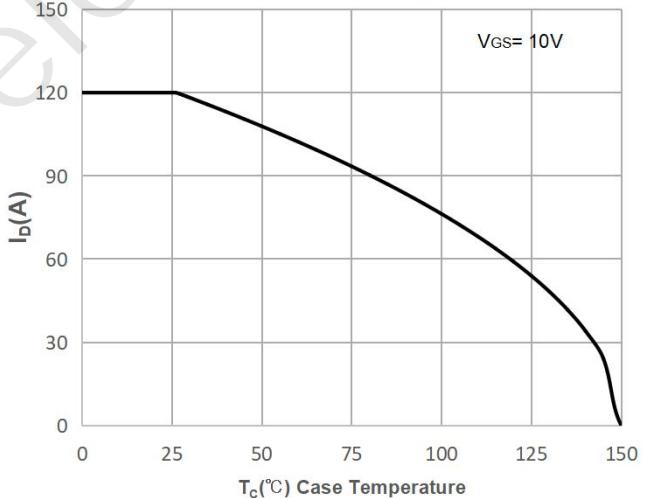


Figure 11: Normalized Maximum Transient Thermal Impedance

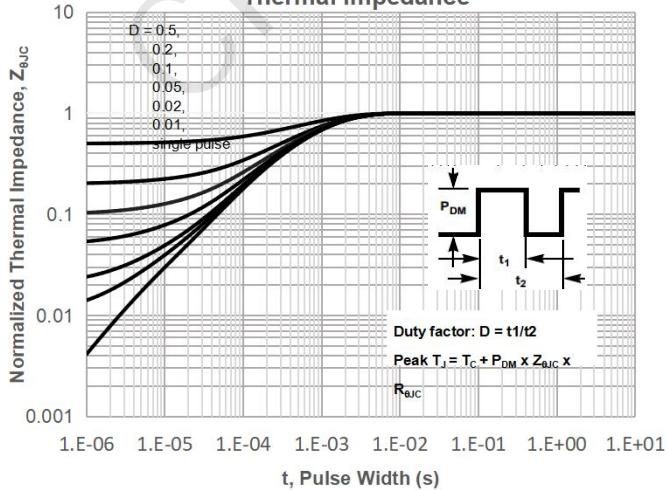
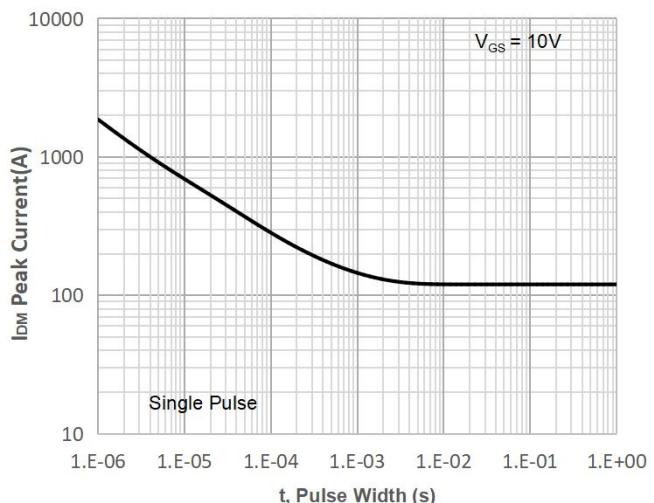


Figure 12: Peak Current Capacity



Test Circuit

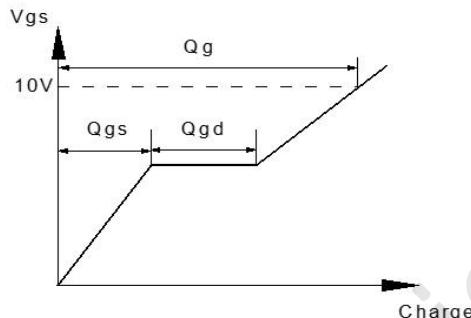
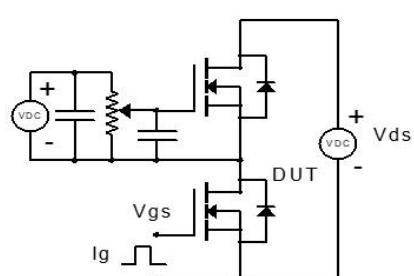


Figure 1: Gate Charge Test Circuit & Waveform

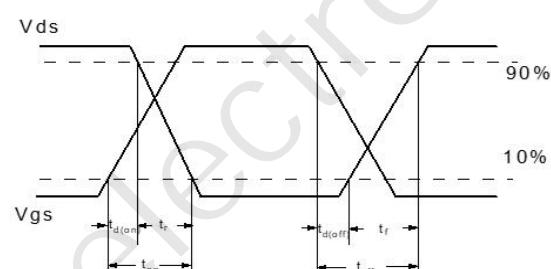
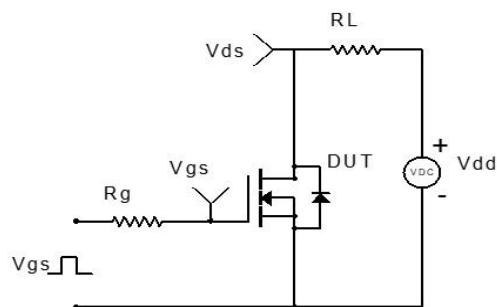


Figure 2: Resistive Switching Test Circuit & Waveform

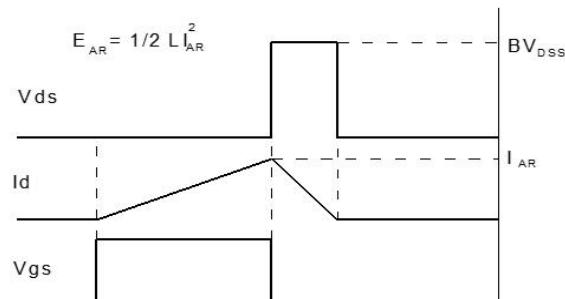
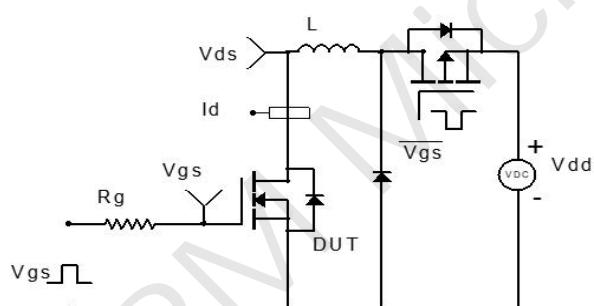


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

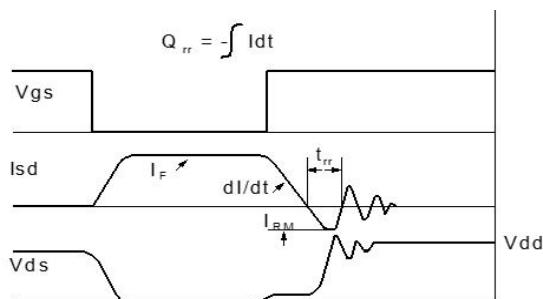
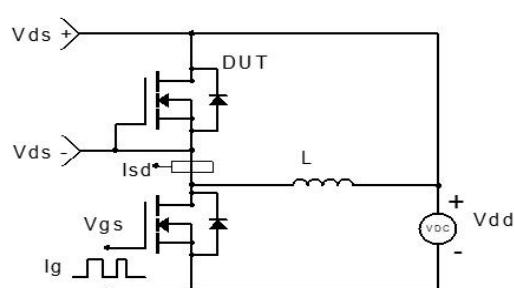
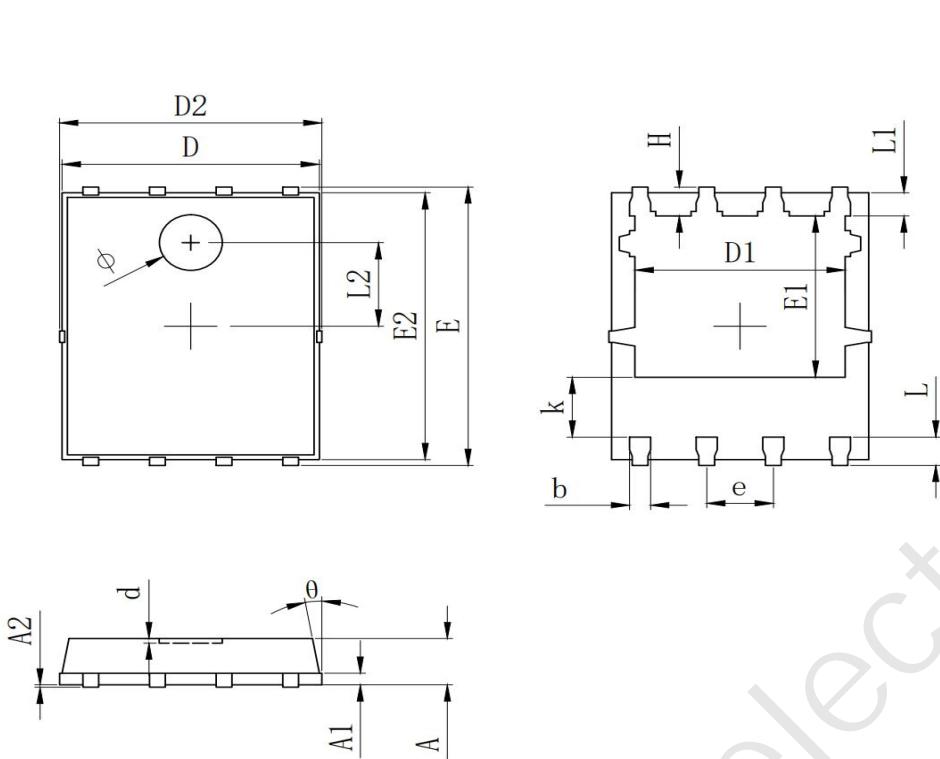


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
ϕ	1.100	1.200	1.300
d	0.100		

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